

CLAIMS

What is claimed:

1. A method of producing a device for securing conductors, the method comprising the steps of:
 - 5 shaping a connector device to include bendable flaps for securing a conductor; and
 - forming the connector device to include an external surface that is eventually affixed to a substantially complementary shaped surface, at least a portion of the conductor secured in the connector device also being affixed to the
 - 10 substantially complementary shaped surface, the conductor being bent near the connector device in a manner so that at least a portion of the conductor and the external surface of the connector device lie in a common contour.
2. A method as in claim 1, wherein the external surface is substantially flat and at least a portion of the conductor and external surface lie in a common plane.
- 15 3. A method as in claim 1 further comprising the steps of:
 - providing a strip of flat metal; and
 - bending the strip of flat metal to form the bendable flaps of a connector device, a portion of the strip of flat metal forming the external surface that is eventually attached to the complementary surface.
- 20 4. A method as in claim 1, wherein the connector device includes two or more sets of bendable flaps.
5. A method as in claim 1, wherein the connector device is electrically conductive.

6. A method as in claim 1, wherein the external surface of the connector device is soldered to a complementary shaped surface.
7. A method as in claim 1, wherein a lead is crimped to the conductor via the connector device.
- 5 8. A method as in claim 1 further comprising the step of:
shaping the connector device to include a tongue for attaching a lead wire.
9. A method as in claim 8, wherein a lead wire can be removably attached to the tongue.
- 10 10. A method as in claim 9, wherein the tongue is disposed above a corresponding surface to which the connector device is attached.
11. A method of attaching conductors comprising the steps of:
providing a connector device having bendable flaps for securing a conductor strip when the flaps are crimped, the connector device including an
15 external surface for attachment to a substantially complementary shaped surface;
crimping at least a portion of the conductor strip to the connector device by bending the flaps; and
attaching the connector device and at least a portion of the conductor strip to the substantially complementary surface, the conductor being bent near
20 the connector device in a manner so that at least a portion of the conductor and the external surface of the connector device lie in a common contour.

12. A method as in claim 11, wherein the step of crimping further comprises:
bending the set of flaps of the connector device inwards towards each other to secure a lead wire to the conductor strip.
13. A method as in claim 11, wherein the connector device is crimped around a
5 lengthwise portion of the conductor strip to attach a distal end of a lead wire to the conductor strip.
14. A method as in claim 11, wherein the connector device is electrically conductive.
15. A method as in claim 11 further comprising the steps of:
disposing a lead wire above the conductor strip and thereafter crimping
10 the flaps of the connector device to attach the lead wire to the conductor strip;
and
bending a portion of the conductor strip extending through the connector device such that at least a portion of the conductor strip lies in a common plane with the external surface of the connector device.
- 15 16. A method as in claim 15, wherein the step of bending a portion of the conductor strip includes applying a force on a portion of the conductor strip extending beyond an edge of the connector device.
17. A method as in claim 11, wherein the conductor strip includes a braided wire.
18. A method as in claim 11, wherein the conductor strip comprises a braided wire
20 with a solder core.

19. A method as in claim 11 further comprising the steps of:
contacting the external surface of the connector device to the
complementary shaped surface; and
applying heat to the connector device for soldering the connector device
5 to the complementary shaped surface.
20. A method as in claim 19, wherein the complementary shaped surface is a layer of
glass.
21. A method as in claim 11 further comprising the step of:
applying heat to the conductor strip and connector device for attachment
10 to glass.
22. A method as in claim 11 further comprising the step of:
bending the flaps of the connector device to crimp a lead wire to a braid
of wire.
23. A method as in claim 22 further comprising the steps of:
15 heating the braid of wire; and
applying solder to the braid of wire.
24. A method as in claim 11 further comprising the step of:
attaching individual solder masses along the conductor strip.

25. A method of forming an assembly comprising:

providing a conductor;

securing a connector device to the conductor by crimping bendable flaps
extending from the connector device, the connector device having an external

5 surface; and

bending the conductor near the connector device in a manner so that at
least a portion of the conductor and the external surface of the connector device
lie in a common contour for attaching to a surface.